

PROPRIETARY

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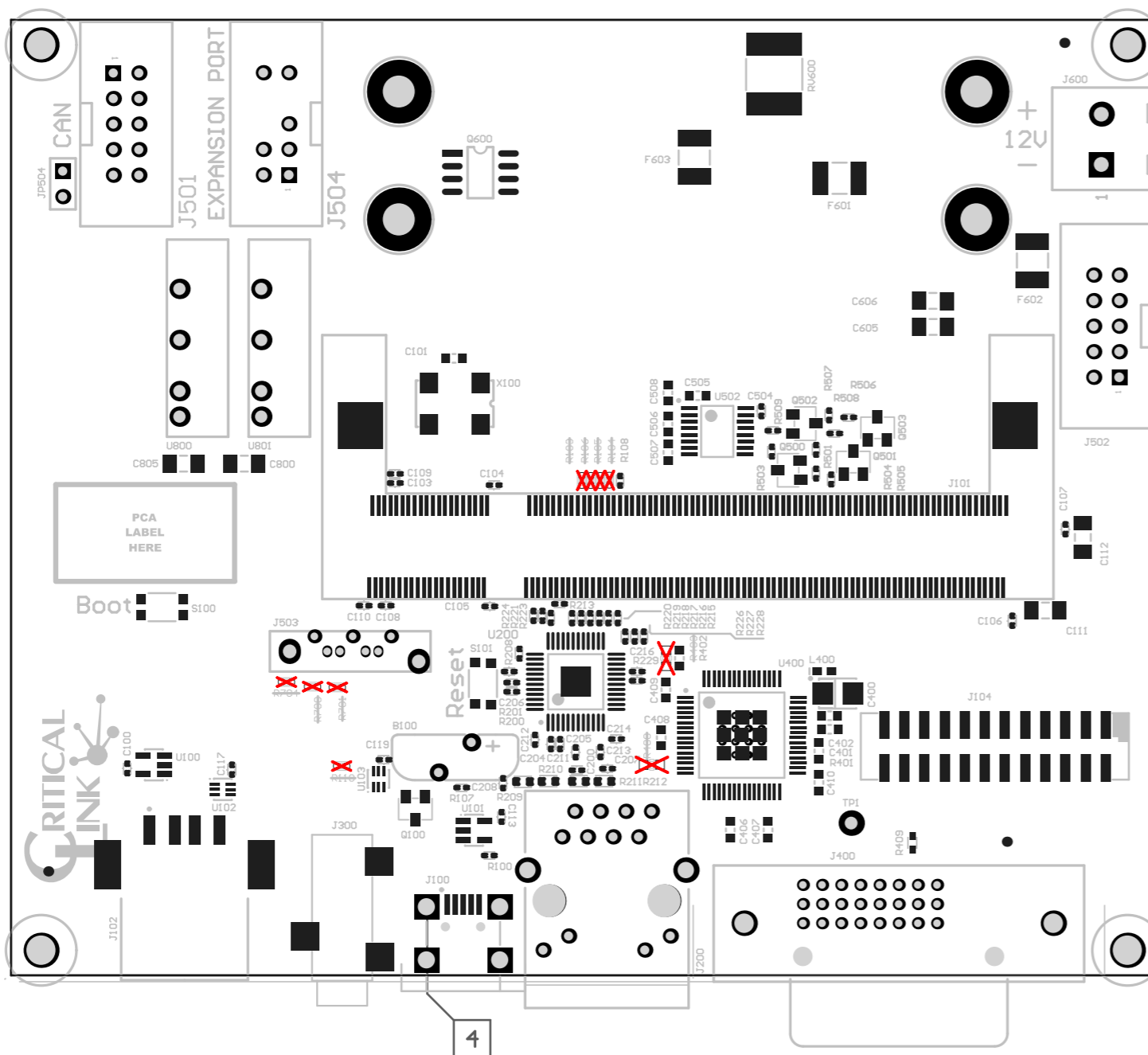
General Notes:


All dimensions are in mils (0.001") unless otherwise specified.
Tolerance on all dimensions shall be ±0.005" unless otherwise specified.

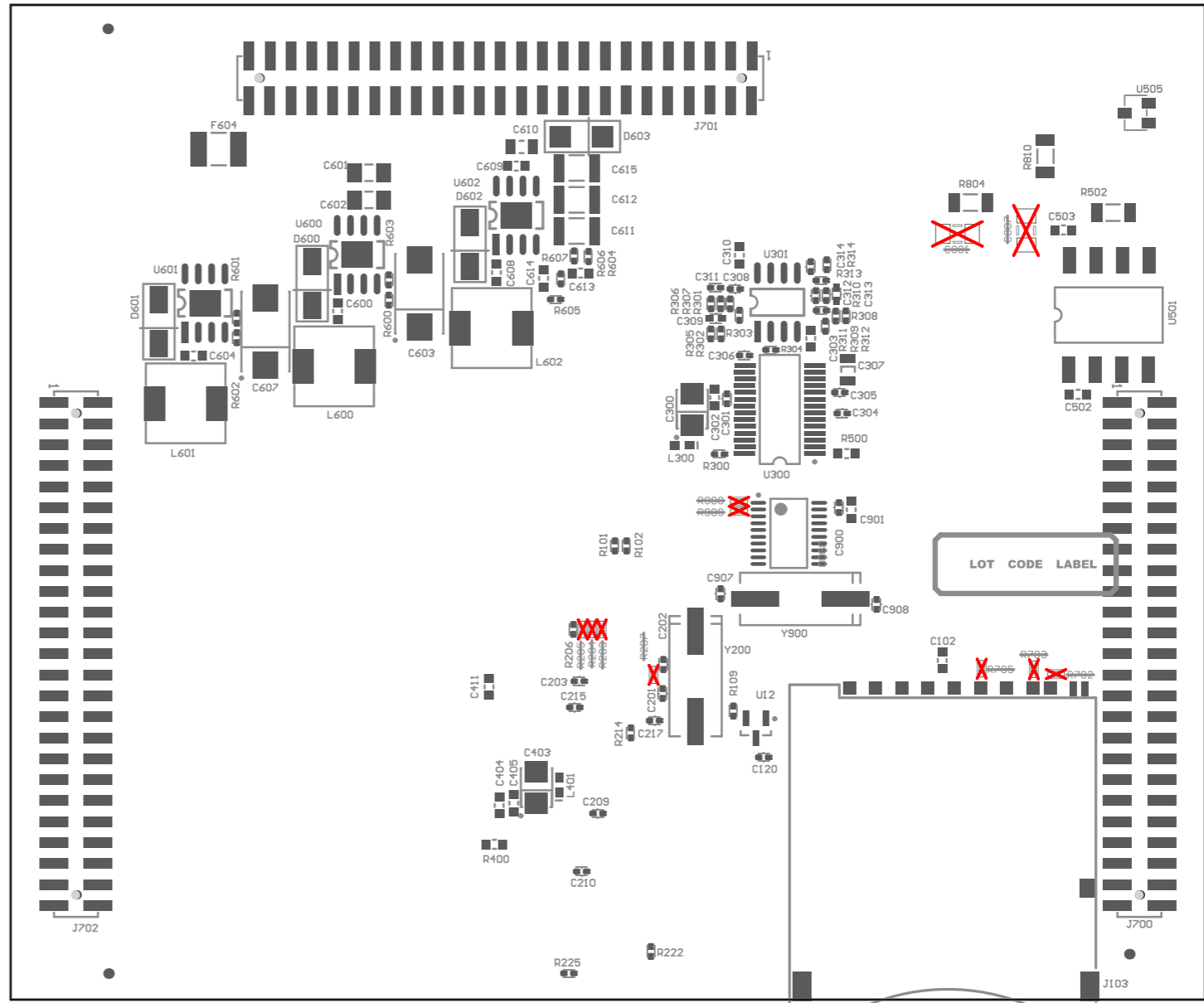
Assembly Notes:


1. Assemble board per IPC A-610C Class II.
2. RoHS compliant, Lead-Free solder process required.
3. Assembly should be flux and residue free
4. Inspect J100 for proper solder flow around through hole pins

ECR	REV	DESCRIPTION	INITIALS	DATE
	1C	ECR 265	AC	7/9/10
	2A	ECR 352	AC	4/21/11
	2B	ECR 370	AC	6/30/11
	2C	ECR 429	AC	11/7/12
740	3A	Removed ID resistor from USB OTG	AC	7/25/14
769	3B	Updated footprints for DFM, updated reset circuit	AC	11/7/14



ENGINEER: AChkourko	TITLE: PCA, OMAP Industrial IO board			 Critical Link, LLC 6712 Brooklawn Pkwy Syracuse, NY 13211 <small>315.425.4045</small> www.criticallink.com
PCB DESIGNER: ACHKOURKO	PART NO.:	80-000268RI-3	REV: B SIZE: A	
DATE: 11/7/2014	PRINT NAME:	Top Assembly Drawing	SCALE: SCALE: 1.00	
FILE NAME: IndustrialIO.PcbDoc				



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